

1. General description

Dual ultrafast power diodes in a TO3PF plastic package.

2. Features and benefits

- Very low on-state loss
- Reduces switching losses in associated MOSFET or IGBT
- Low leakage current
- Isolated plastic package

3. Applications

- Active PFC in air conditioner
- S.M.P.S Power Factor Correction (PFC)
- Half-bridge/full-bridge switched-mode power supplies

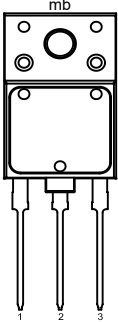
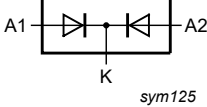
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V _R	reverse voltage	DC		-	-	600	V
I _{F(AV)}	average forward current	δ = 0.5 ; T _h ≤ 101 °C; square-wave pulse; Fig. 1 ; Fig. 2 ; Fig. 3		-	-	15	A
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _h ≤ 101 °C; Square-wave pulse		-	-	30	A
I _{FSM}	non-repetitive peak forward current	t _p = 10 ms; T _{j(init)} = 25 °C; sine-wave pulse; per diode; Fig. 4		-	-	150	A
		t _p = 8.3 ms; T _{j(init)} = 25 °C; sine-wave pulse; per diode		-	-	165	A
Static characteristics							
V _F	forward voltage	I _F = 15 A; T _j = 25 °C; Fig. 6		-	1.17	1.4	V
		I _F = 15 A; T _j = 150 °C; Fig. 6		-	1	-	V
Dynamic characteristics							
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; Fig. 7		-	38	-	ns
		I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	67	-	ns
		I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7		-	106	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1	 <p>TO3PF</p>	
2	K	cathode		
3	A2	anode 2		
mb	mb	mounting base		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYV415J-600P	TO3PF	Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-3P ‘full pack’	TO3PF

7. Limiting values

Table 4. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{RRM}	repetitive peak reverse voltage		-	600	V
V _{RWM}	crest working reverse voltage		-	600	V
V _R	reverse voltage	DC	-	600	V
I _{F(AV)}	average forward current	δ = 0.5 ; T _h ≤ 101 °C; square-wave pulse; Fig. 1; Fig. 2; Fig. 3	-	15	A
I _{O(AV)}	average output current	δ = 0.5 ; T _h ≤ 90 °C; square-wave pulse; both diodes conducting	-	30	A
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _h ≤ 101 °C; Square-wave pulse	-	30	A
I _{FSM}	non-repetitive peak forward current	t _p = 10 ms; T _{j(init)} = 25 °C; sine-wave pulse; per diode; Fig. 4	-	150	A
		t _p = 8.3 ms; T _{j(init)} = 25 °C; sine-wave pulse; per diode	-	165	A
T _{stg}	storage temperature		-65	175	°C
T _j	junction temperature		-	175	°C

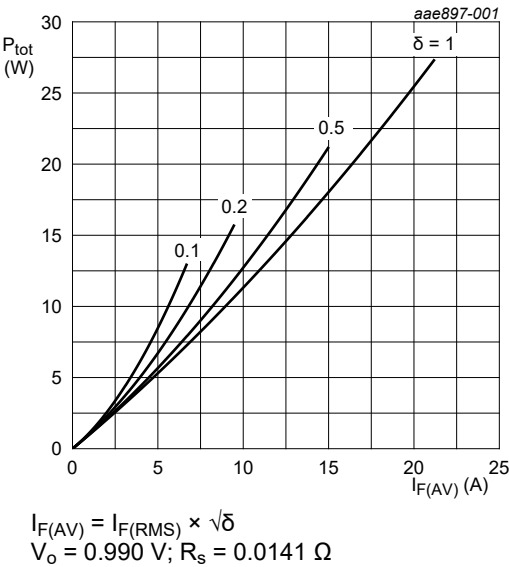


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values; per diode

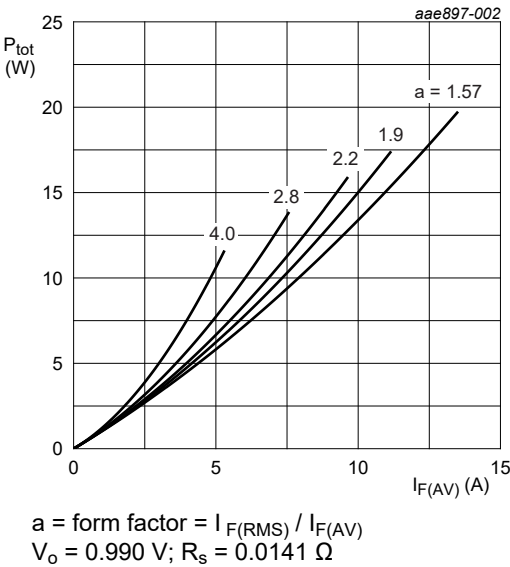


Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values; per diode

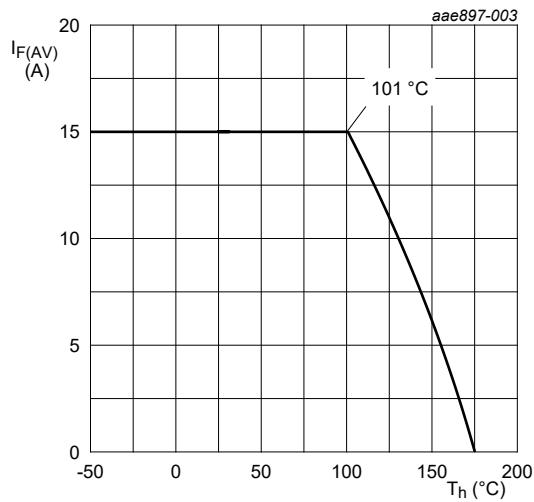


Fig. 3. Average forward current as a function of heatsink temperature; maximum values; per diode

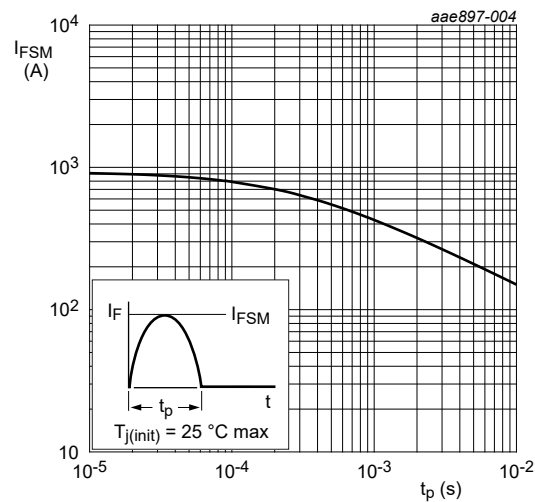


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values; per diode

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to heatsink	with heatsink compound; per diode; Fig. 5	-	2.9	3.5	K/W
		with heatsink compound; both diodes conducting	-	1.6	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	35	-	K/W

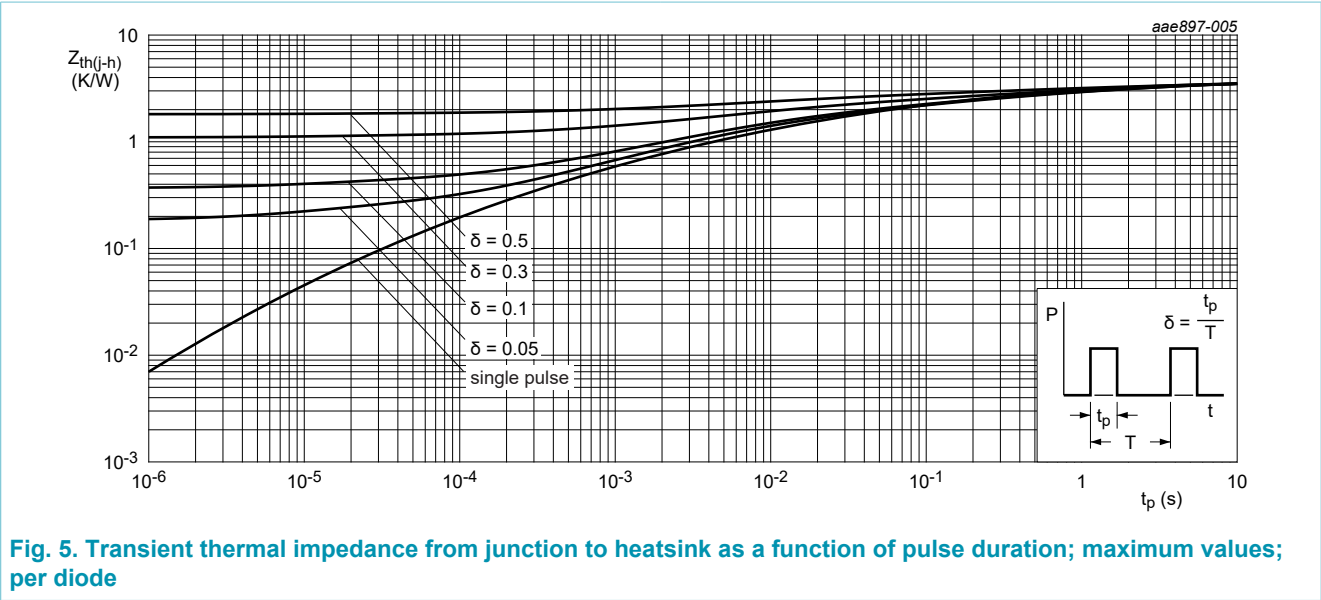


Fig. 5. Transient thermal impedance from junction to heatsink as a function of pulse duration; maximum values; per diode

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 15 A; T _j = 25 °C; Fig. 6		-	1.17	1.4	V
		I _F = 15 A; T _j = 150 °C; Fig. 6		-	1	-	V
I _R	reverse current	V _R = 600 V; T _j = 25 °C		-	-	10	μA
		V _R = 600 V; T _j = 150 °C		-	-	500	μA
Dynamic characteristics							
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; Fig. 7		-	38	-	ns
		I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	67	-	ns
		I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7		-	106	-	ns
I _{RM}	peak reverse recovery current	I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	9.8	-	A
		I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7		-	16	-	A
Q _r	recovered charge	I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	329	-	nC
		I _F = 15 A; V _R = 200 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7		-	876	-	nC

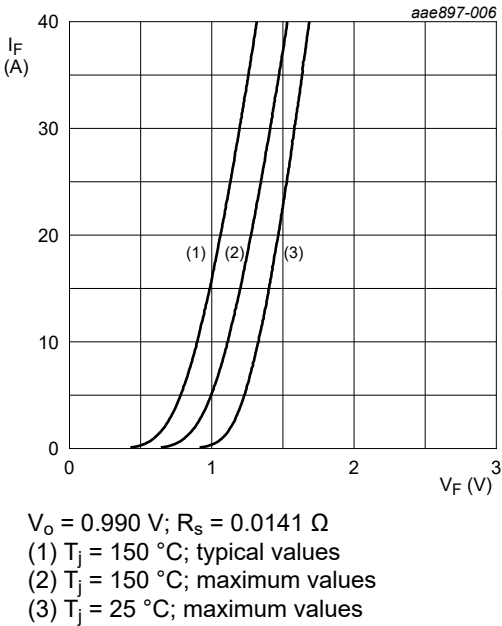


Fig. 6. Forward current as a function of forward voltage, per diode

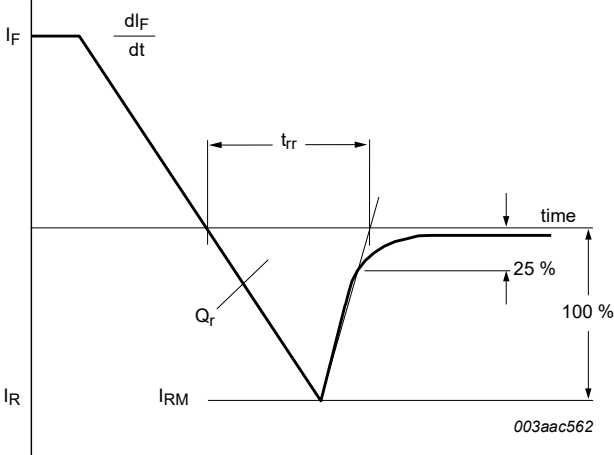


Fig. 7.

10. Package outline

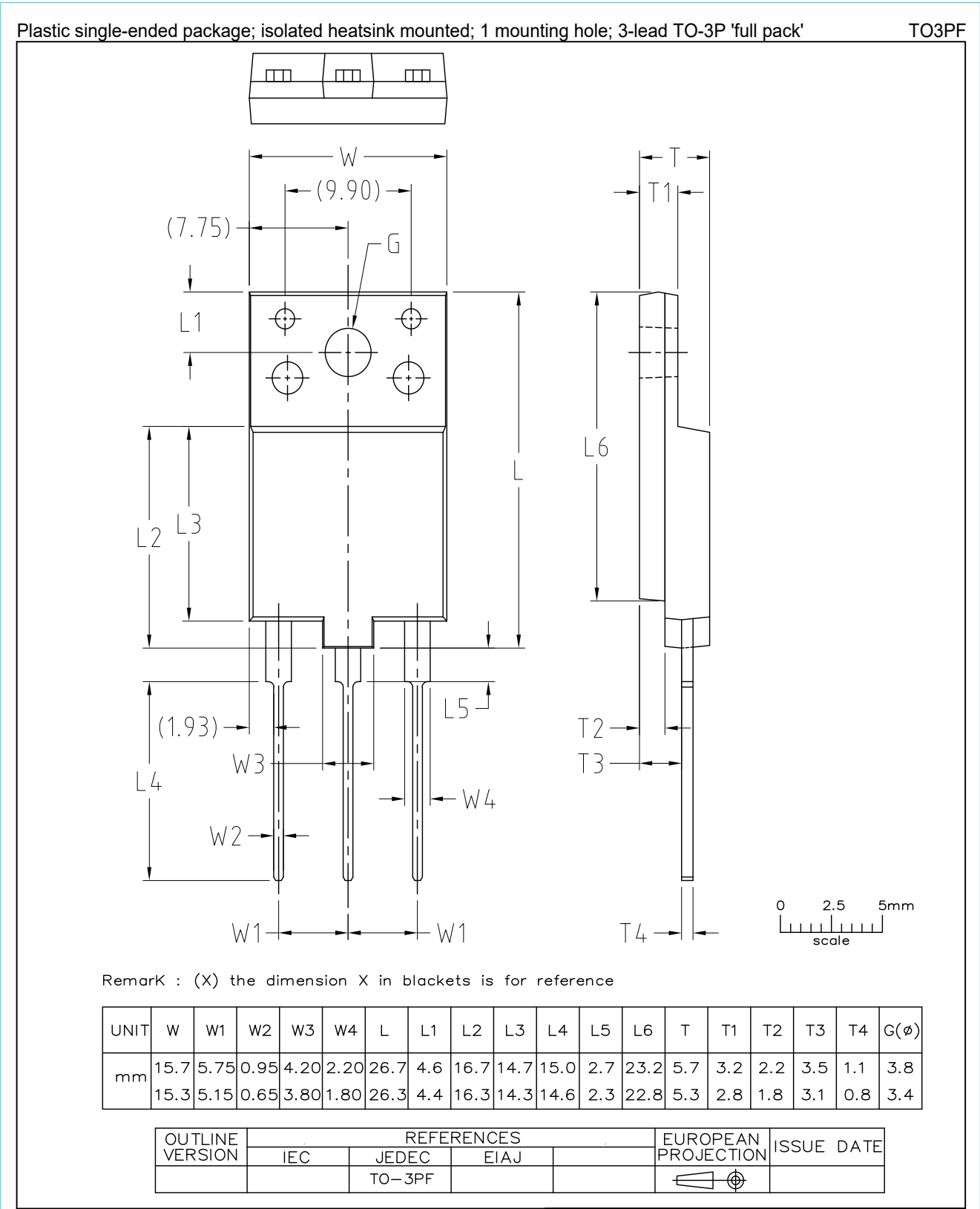


Fig. 8. Package outline TO3PF

11. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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Date of release: 22 February 2018